ThermaView℠

Solutions engineered for thermal imaging applications

CMOS Readout ICs

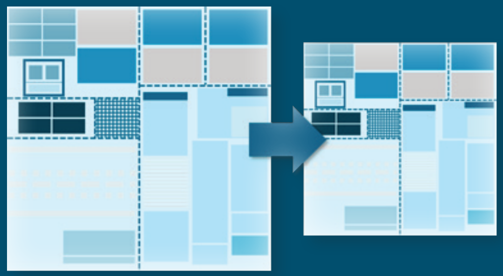
ThermaView℠ solutions enable the most advanced state-side ROICs for next generation thermal imaging systems.

Built on our 90 nm CMOS platform, ThermaView ROIC solutions offer high-performance IC readout technology with low-noise, scalable designs engineered to support mission-critical requirements.

High-density routing technology maximizes component density within the pixel cell

Our ROIC platform employs two local interconnect layers — enabling short, efficient connections that perform like an additional routing layer, without the need for vias.

- 15% area improvement in chip density as compared to 90 nm technology with a conventional contact layer.
- Enables high-density feature integration within each pixel.



The features ROIC designers want, the Trusted support they need

- Fine Pixel Pitch, High-Resolution Focal Plane Arrays
- Large Format via Reticle Stitching
- FPA Bonding Prep
- Trusted Supply Chain for Mission-Critical Reliability

Specialized Support for Mission Systems Production Processes

- Support for low-rate, long life-cycle defense mission applications
- Security protocols for secure and Trusted programs
- DMEA Category 1A Trusted Supplier Accreditation

High-Volume, High-Performance for Industrial & Automotive Applications

- ThermaView ROICs provide the reliability and scalability to power advanced manufacturing and automation.
- IATF16949 Automotive Certification

ThermaView S90LN Key Features

- 200 mm wafers
- 90 nm CMOS, 7 metal layers
- 1.2 V core; 1.8 V, 2.5 V and 3.3 V IO
- Temp range: -55° C to 125° C
- Cryogenic models: 77 K to 150 K
- Die stitching
- Planarized top vias
- Rad-tolerant by process up to: request radiation report
- Dual MIM caps: 2 fF/μm^2
- High-density MIM caps: 6.5 fF/μm^2

Let's make your next project a reality.

Connect with us at skywatertechnology.com